

ABSTRACT

To provide a retaining ring for holding semiconductor wafers in a chemical mechanical polishing apparatus, with not only the edge effect but also, inter alia, the time-consuming and costly exchanging of the plastic portion joined with epoxy adhesive to the metal ring being avoided, it is proposed that the retaining ring be of integral design and be made of a plastic material, and the retaining ring form on a first front side thereof a bearing surface for supporting the retaining ring on a polishing surface of the polishing apparatus, and include on the side thereof lying opposite the first front side thereof in axial direction fitting elements for fitting the retaining ring on the polishing apparatus.